SPEC. No. ED-05G080A ISSUE April 4, 2008

SHARP

OPTO-ELECTRONIC DEVICES DIVISION ELECTRONIC COMPONENTS AND DEVICES GROUP SHARP CORPORATION

SPECIFICATION

DEVICE SPECIFICA	TION FOR	
MODEL No.	PHOTOINTERRUPTER GP1S194HCZ0F	
Specified for		
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Y. Oda,
Department General Manager of
Engineering Dept., III
Opto-Analog Devices Div.
Electronic Components and Devices Group
SHARP CORPORATION



Product name: PHOTOINTERRUPTER

Model No.: GP1S194HCZ0F

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- When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets, as well as the precautions mentioned below. Sharp assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets, and the precautions mentioned below.

(Precautions)

- (1) This product is designed for use in the following application areas:
 - OA equipment Audio visual equipment Home appliances
 - Telecommunication equipment (Terminal)
 Measuring equipment
 - Tooling machines
 Computers

If the use of the product in the above application areas is for equipment listed in paragraphs (2) or (3), please be sure to observe the precautions given in those respective paragraphs.

- (2) Appropriate measures, such as fail-safe design and redundant design considering the safety design of the overall system and equipment, should be taken to ensure reliability and safety when this product is used for equipment which demands high reliability and safety in function and precision, such as ;
 - Transportation control and safety equipment (aircraft, train, automobile etc.)
 - Traffic signals Gas leakage sensor breakers Rescue and security equipment
 - · Other safety equipment
- (3) Please do not use this product for equipment which require extremely high reliability and safety in function and precision, such as;
 - Space equipment Telecommunication equipment (for trunk lines)
 - Nuclear power control equipment Medical equipment
- (4) Please contact and consult with a Sharp sales representative if there are any questions regarding interpretation of the above three paragraphs.
- 3. Please contact and consult with a Sharp sales representative for any questions about this product.

1. Application

This specification applies to the outline and characteristics of transmissive type photointerrupter; M



- 2. Outline: Refer to the attached drawing No. CY12950i02.
- 3. Ratings and characteristics: Refer to the attached sheet, Page 5, 6, 7.
- 4. Reliability: Refer to the attached sheet, Page 8.
- 5. Outgoing inspection: Refer to the attached sheet, Page 9.
- 6. Supplements
 - 6.1 Parts

Refer to the attached sheet, Page 10.

6.2 ODS materials

This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS : CFC_S, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

6.3 Specified brominated flame retardants

Specified brominated flame retardants (PBB and PBDE) are not used in this device at all.

- 6.4 Compliance with each regulation
 - 6.4.1 The RoHS directive(2002/95/EC)

This product complies with the RoHS directive(2002/95/EC).

Object substances: mercury, lead, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE)

6.4.2 Content of six substances specified in Management Methods for Control of Pollution Caused by Electronic Information Products Regulation (Chinese: 电子信息产品污染控制管理办法).

Category	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent chromium (Cr ⁶⁺)	Polybrominate d biphenyls	Polybrominated diphenyl ethers
Photointerrupter	1	1	1	(CI)	(PBB) ✓	(PBDE) ✓

- : indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006 standard.
- 6.5 Product mass: Approx. 24mg
- 6.6 Packing

Refer to the attached drawing No. CY12951i09B



7. Notes

1) Circuit design

In circuit designing, make allowance for the degradation of the light emitting diode output that results from long continuous operation. (50% degradation/5 years)

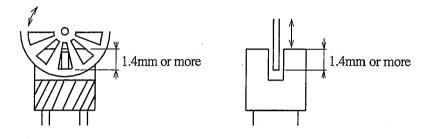
2) Prevention of detection error

To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

3) Position of opaque board

Opaque board shall be installed at place 1.4mm or more from the top of elements.

(Example)



4) Soldering

To solder onto lead pins, solder at the position of 0.3mm or more from the package's bottom at 260°C for 3 s or less.

Please don't bend lead pins from the root of package when soldering.

Please also take care not to let any external force exert on lead pins.

Please don't do soldering with preheating, and please don't do soldering by reflow.

Please have soldering adjustment, etc. after GP1S194HCZ0F is cooled down, and also note that the outer mold resin may be meltdown by heating for a long time.

5) Cleaning

Cleaning shall be carried out under the below conditions to avoid keeping solvent, solder and flux on the device.

- (1) Solvent cleaning: Solvent temperature 45°C or less, Immersion for 3 min. or less
- (2) Ultrasonic cleaning: Since the influence to the product may changes by the conditions of the ultrasonic power, time, the tank size, PCB size, the product installation condition, etc., please evaluate with actual conditions and confirm before usage.
- (3) The cleaning shall be carried out with solvent below.

Solvent: Ethyl alcohol, Methyl alcohol

6) Lead pin

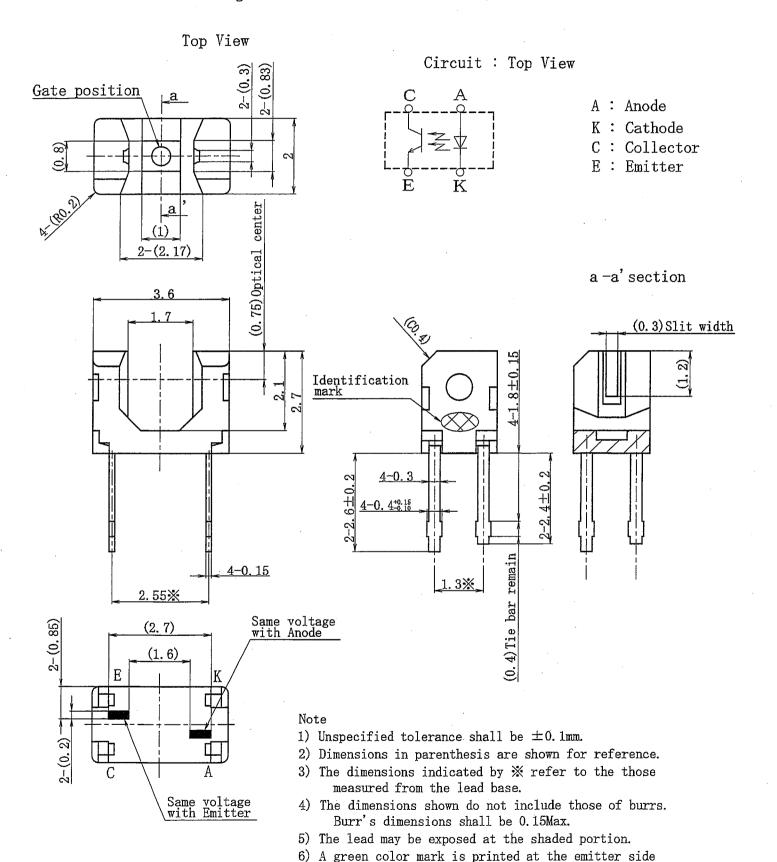
Lead terminals of this product are tin copper alloy plated. Before usage, please evaluate solder ability with actual conditions and confirm. The uniformity in color for the lead terminals are not specified.

2.1 Outline Dimensions

Drawing No. CY12950i02

Scale : 10/1

Unit: mm



- for identifying the direction.
- 7) The edge surface of the tie bar remains has poor solderability due to no plating, so please select a proper PCB thickness to avoid any influences. 1.2mm thickness shall be recommended.



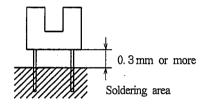
3. Ratings and characteristics

3.1 Absolute maximum ratings

Ta-259	$\overline{}$
12-20	٠,

				14 25 0
	Parameter	Symbol	Rating	Unit
	Forward current	$I_{\mathbf{F}}$	30	mA
Input	Reverse voltage	V _R	6	V
	Power dissipation	P	75	mW
	Collector-emitter voltage	V _{CEO}	35	V
Output	Emitter-collector voltage	V _{ECO}	6	V
Output	Collector current	Ic	20	mA
	Collector power dissipation	Pc	75	mW
	Total power dissipation	Ptot	100	mW
	Operating temperature	Topr	-25 to +85	°C
	Storage temperature	Tstg	-40 to +100	℃
	* Soldering temperature	Tsol	260	င

* Soldering time: 3 s or less

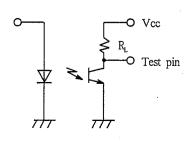


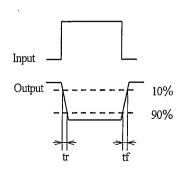
3.2 Electro-optical characteristics

Ta=25°C

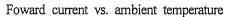
	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		V_{F}	I _F =20mA	••	1.2	1.4	V
Input	Reverse current		I_R	V _R =3V	-	-	10	μΑ
Output	Collector dark curr	ent	I _{CEO}	V _{CE} =20V	-		100	nA
	Collector current		Ic	V _{CE} =5V, I _F =5mA	150	-	600	μΑ
Transfer	Posnonso timo	(Rise)	tr	V _{CE} =5V, Ic=100 μ A	-	50	150	μs
character-	Response time	(Fall)	tf	$R_L=1k\Omega$	-	50	150	μs
is tics	Collector-emitter saturation voltage		V _{CE} (sat)	I _F =10mA, Ic=40 μ A	-	_	0.4	V

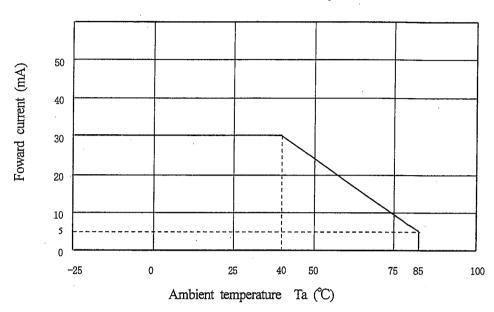
(Test circuit for response time)



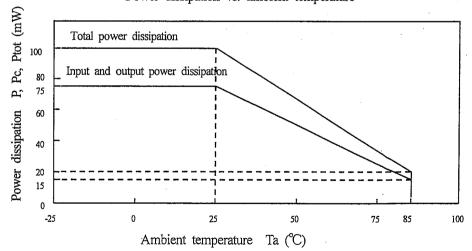






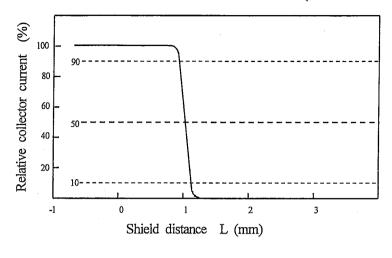


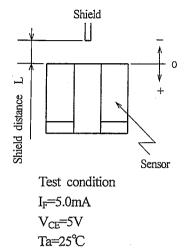
Power dissipation vs. ambient temperature



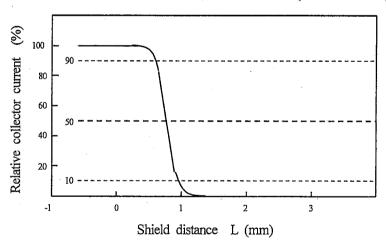


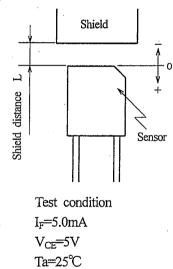
Relative collector current vs. shield distance 1 (Reference value)





Relative collector current vs. shield distance 2 (Reference value)





4. Reliability

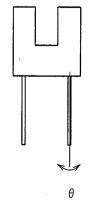
The reliability of products shall satisfy items listed below.

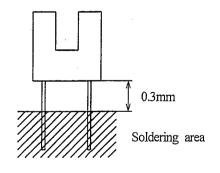
Confidence level: 90%

		LTPD: 10	or 20
Test Items	Test Conditions	Failure Judgment Criteria	Samples (n) Defective (c)
Temperature cycling	1 cycle -40°C to +100°C (30min) (30min) 20 cycles test		n=22, c=0
humidity storage	+60°C, 90%RH, 500h		n=22, c=0
High temp. storage	+100°C, 500h		n=22, c=0
Low temp. storage	-40°C, 500h	$I_R \geqq U \times 2$	n=22, c=0
Operation life	I _F =20mA, Ta=25°C, 500h	7 77770	n=22, c=0
Mechanical shock	15000m/s ² , 0.5ms 3 times/ \pm X, \pm Y, \pm Z direction	$I_{CEO} \ge U \times 2$ $V_F \ge U \times 1.2$	n=11, c=0
Variable frequency vibration	100 to 2000 to 100Hz/20min 2h/X, Y, Z direction 100m/s ²	Ic≦L×0.8	n=11, c=0
Terminal strength (Tension)	Weight: 3.0N 30s/each terminal	U: Upper specification limit	n=11, c=0
Terminal strength (Bending) *1	Weight: 1.0N $0^{\circ} \rightarrow 90^{\circ} \rightarrow 0^{\circ} \rightarrow -90^{\circ} \rightarrow 0$ 1 time bending	L: Lower specification limit	n=11, c=0
Soldering heat *2	260°C, 3s Immerse up to 0.3mm from the bottom face of package.		n=11, c=0
Solder ability *2, *3	245°C, 3s Prior disposition: Dip rogin flux. Then immerse up to 0.3mm from the bottom face of package.	Judgment only appearance Solder shall adhere at less than 95% area of immersed portion of lead except the tie bar remain portions.	n=11, c=0

^{* 1} Terminal bending direction is shown below.

*2 Soldering area is shown below.





^{*3} The alloy composition of solder used for lead free should be Sn-2.5Ag-1Bi-0.5Cu or Sn-3.0Ag-0.5Cu. Flux used for precleaning should be equivalent to EC-19S-8(TAMURA KAKEN CORPORATION).



- 5. Outgoing inspection
- 5.1 Inspection items
- (1) Electrical characteristics

 V_{F} , I_{R} , BV_{ECO} , BV_{CEO} , I_{C} , I_{CEO} , $V_{\text{CE(sat)}}$

- (2) Appearance
- 5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on ISO 2859 is applied. The AQL according to the inspection items are shown below.

Defect	Inspection item	AQL(%)
Major defect	Characteristics defect	0.065
Minor defect	Defects on appearance *	0.25

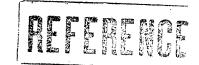
* Crack ··· Visible crack shall be defect.

Split

* Chip Scratch

The others

One which affects the electrical characteristics shall be defect.



6. Supplements

6.1 Parts

This product uses the below parts.

6.1.1 Light detector (Quantity: 1)

Туре	Material	Maximum sensitivity (nm)	Sensitivity (nm)	Response time (μ s)
Phototransistor	Silicon (Si)	930	700 to 1200	20

6.1.2 Light emitter (Quantity: 1)

Туре	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared light emitting diode (non-coherent)	GaAs	950	0.3

6.1.3 Material

Case	Lead frame	Lead frame plating
Black PPS resin (UL 94V-0)	42 Alloy	SnCu plating

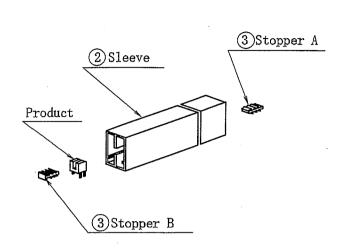
6.1.4 Others

This product shall not be proof against radiation flux.

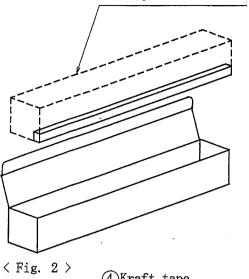
6.6 Packing (Drawing No. CY12951i09B)



Sleeve containing the product (5 steps of 10 rows)



< Fig. 1 >



(Fig. 2)

(A) Kraft tape

(D) Packing case

Indication phase

< Fig. 3 >

1. Packing material

Νo	Name	material	The number of use
1	Packing case	Paper corrugated cardboard	1
2	Sleeve	Polycarbonate	50
3	Stopper A, B	rubber	50, respectively
4	Kraft tape		_

2. Packing quantity

- 1. Packing sleeve: 200pieces per 1 sleeve
- 2. Packing case: 10000pieces per 1 case

(Gross weight: Approx 850 g)

3. Indication items

The contents of the carton indication conforms to EIAJ C-3 and the following items are indicated.

Model No., Internal production control name, Quantity, Packing date, Corporate name, Country of origin

4. Packing method

- 1. 200 products are contained to a sleeve.

 (The receipt method is shown in the above figure.) <Fig. 1>
- 2. 50 sleeves (5 steps of 10 rows) are contained into a packing case. <Fig. 2>
- 3. The packing case is sealed off with the kraft tape.

 Indicates on the packing case Model No., Internal production control name, Quantity, Packing date, Corporate name, Country of origin. <Fig. 3>